



Spec No.: DS70-2009-0001 Effective Date: 04/12/2016

Revision: A

LITE-ON DCC

RELEASE

BNS-OD-FC001/A4



1. DESCRIPTION

These high gain series couplers use a light emitter diode and an integrated high gain photo detector to provide extremely high current transfer ratio between input and output. Separate pins for the photodiode and output stage result in TTL compatible saturation voltage and high speed operation. Where desired the Vcc and Vo terminals may be tied together to achieve conventional photo Darlington operation. A base access terminal allows a gain bandwidth adjustment to be made.

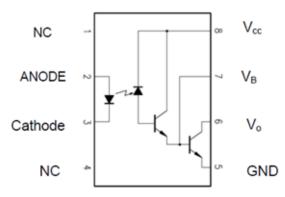
1.1 Features

- High current transfer ratio 2000% typical.
- Low input current requirements 0.5mA
- High output current 60mA
- CTR guarantee $0\sim70^{\circ}$ C.
- Instantaneous common mode rejection 10KV/µsec
- lacktriangleq TTL compatible output 0.1V V_{OL} typical
- UL, CSA approved.

1.2 Applications

- Digital logic ground isolation
- Low input current line receiver
- Telephone ring detector
- EIA-RS-232C line receiver
- Current loop receiver
- High common mode noise line receiver

1.3 Functional Diagram



A 0.1µF bypass Capacitor must be connected between Pin8 and Pin5

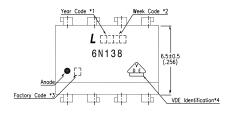
Truth Table (Positive Logic)

LED	OUT
ON	L
OFF	Н

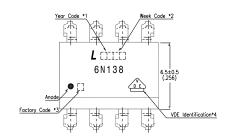


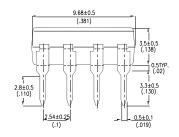
2. PACKAGE DIMENSIONS

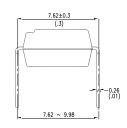
2.1 6N138-L

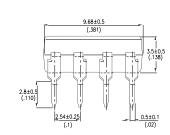


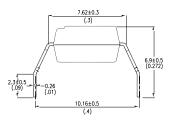
2.2 6N138M-L



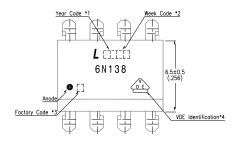


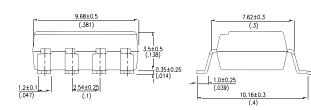






2.3 6N138S-L





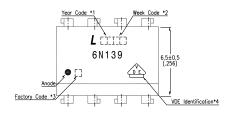
Notes:

- 1. Year date code.
- 2. 2-digit work week.
- 3. Factory identification mark shall be marked (Y: Thailand , W: China-CZ)
- 4. For VDE option.

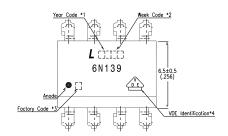
Dimensions in millimeters (inches).

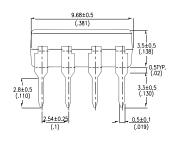


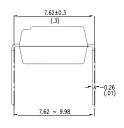
2.4 6N139-L

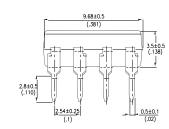


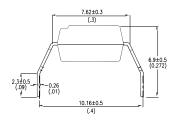
2.5 6N139M-L



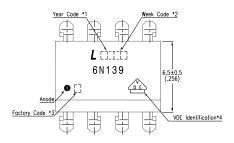


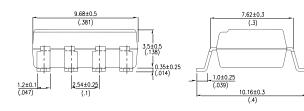






2.6 6N139S-L





Notes:

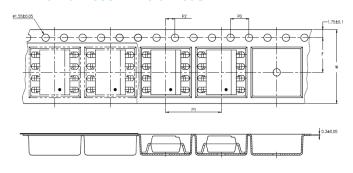
- 1. Year date code.
- 2. 2-digit work week.
- Factory identification mark shall be marked (Y: Thailand , W: China-CZ)
- 4. For VDE option.

Dimensions in millimeters (inches).

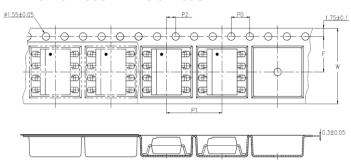


3. TAPING DIMENSIONS

3.1 6N138S-TA-L/ 6N139S-TA-L



3.2 6N138S-TA1-L/ 6N139S-TA1-L



Description	Symbol	Dimension in mm (inch)
Tape wide	W	16±0.3 (0.63)
Pitch of sprocket holes	P ₀	4±0.1 (0.15)
Distance of compartment	F	7.5±0.1 (0.295)
Distance of compartment	P_2	2±0.1 (0.079)
Distance of compartment to compartment	P ₁	12±0.1 (0.472)

3.3 Quantities Per Reel

Package Type	TA / TA1
Quantities (pcs)	1000



4. RATING AND CHARACTERISTICS

4.1 Absolute Maximum Ratings at Ta=25°C *1

	Parameter		Symbol	Rating	Unit	Note
	Average Forward Input Current		l _F	20	mA	2
Input	Reverse Input Voltage		V_{R}	5	V	
	Power Dis	ssipation	Pı	35	mW	
	Output Collec	ctor Current	I _O	50	mA	
Outrot	Outout Valta as	6N138	V	7	\ /	
Output	Output Voltage 6N139		Vo	18	V	
	Output Collector Power Dissipation		P _o	100	mW	
	Isolation	Isolation Voltage		5000	V_{rms}	
	Cumply Voltage	6N138	V	7	V	
	Supply Voltage	6N139	V _{CC}	18	V	
	Operating Te	Operating Temperature		-40 ~ +85	°C	
	Storage Temperature		T_{stg}	-55 ~ +125	°C	
	Lead Solder Temperature *2		T_{sol}	260	°C	

- Ambient temperature = 25°C, unless otherwise specified. Stresses exceeding the absolute maximum ratings can cause permanent damage to the device. Exposure to absolute maximum ratings for long periods of time can adversely affect reliability.
- 2. 260°C for 10 seconds. Refer to Lead Free Reflow Profile.



4.2 ELECTRICAL CHARACTERISTICS at Ta = 25°C

Parameters	Test Condition	Symbol	Device	Min	Тур	Max	Units
Input	Input						
Input Forward Voltage	I _F =1.6mA, T _A =25°C	V_{F}			1.1	1.7	V
Input Forward Voltage Temperature Coefficient	IF=1.6mA	$\Delta V_F/\Delta T_A$	6N138		-1.9		mV/℃
Input Reverse Voltage	I _R = 10μA T _A =25℃	BV_R	6N139	5	-	-	V
Input Capacitance	V _F =0; f=1MH _Z	C _{IN}		-	60	-	pF
Detector							
	I _F =1.6mA; Vo=0.4V; Vcc=4.5V		6N138	300	1600	2600	
Current transfer ratio	rent transfer ratio $I_F=0.5$ mA; Vo=0.4V; Vcc=4.5V CTR 6N139		400	2000	5000	%	
		500	1600	2600			
	I _F =1.6mA; Vcc=4.5V; I _o =4.8mA 6N138 I _F =0.5mA; Vcc=4.5V; I _o =2mA	6N138	-	0.1	0.4		
Logic low output voltage	I _F =1.6mA; Vcc=4.5V; I _o =8mA	V _{OL}	6N139	-	0.1	0.4	V
	I _F =5mA; Vcc=4.5V; I _o =15mA						
	I _F =12mA; Vcc=4.5V; I _o =24mA	-			0.2	-	
	I _F =0mA, Vo=Vcc=7V; T _A =25°C		6N138	-	0.05	250	_
Logic high output current	I _F =0mA, Vo=Vcc=18V; T _A =25°C	I _{OH} 6N1	6N139	-	0.1	100	μ A
Logic low supply current	I _F =1.6mA, V₀=open (Vcc=18V)	I _{ccL}	6N138 6N139	-	0.4	1.5	m A
Logic high supply current	I_F =0mA, V_o =open ; T_A =25 $^{\circ}$ C (Vcc=18V)	I _{ccH}	6N138 6N139	-	0.01	10	m A

Specified over recommended temperature ($T_A = -40^{\circ}C$ to $+85^{\circ}C$, $4.5V \le V_{CC} \le 5.5V$), $I_F = 7.5$ mA unless otherwise specified. All typicals at $T_A = 25^{\circ}C$, $V_{CC} = 5.0V$.



5. SWITCHING SPECIFICATIONS (AC)

Parameter	Test Condition	Symbol	Device	Min	Тур	Max	Units	
	$I_F=1.6$ mA; $R_L=2.2$ k Ω	6N138 t _{PHL} 6N139	6N138	-	1.6	10		
Propagation Delay Time to Low Output Level	I_{F} =0.5mA; R_{L} =4.7K Ω		t _{PHL}	6N120	-	5	25	μ s
zon output zoroi	$I_F=12mA; R_L=270\Omega$		-	0.1	1			
	$I_F=1.6$ mA; $R_L=2.2$ k Ω	t _{PLH}	6N138	-	10	35		
Propagation Delay Time to High Output Level	I_{F} =0.5mA; R_{L} =4.7K Ω		6N139	-	18	60	μ s	
	I_F =12mA; R_L =270 Ω			-	2	7		
Logic High Common Mode	I _F =0mA; V _{CM} =10V _{p-p}	6N138			10		KV/µs	
Transient Immunity	$R_L=2.2K\Omega$	ICIVIHI	СМ _Н 6N139	1	10	-	KV/µs	
Logic Low Common Mode	I _F =1.6mA; V _{CM} =10V _{p-p}	6N138		1	40		KV/µs	
Transient Immunity	R_L =2.2 $K\Omega$	CM _L	СМ _С 6N139		10	-	KV/µs	

^{*}All Typical at T_A=25°C



6. ISOLATION CHARACTERISTIC

Parameter	Symbol	Min.	Тур.	Max.	Unit	Test Condition
Input-Output Insulation Leakage Current	I _{I-O}	_	_	1.0	μΑ	45% RH, t = 5s, V _{I-O} = 3kV DC, T _A =25°C
Withstand Insulation Test Voltage	V _{ISO}	5000	_	_	V_{RMS}	RH \leq 50%, t = 1min, T _A = 25°C
Input-Output Resistance	R _{I-O}	_	10 ¹²	_	Ω	V _{I-O} = 500V DC

^{*}All Typical at T_A=25°C

Notes

- 1. AC For 1 Minute, R.H. = 40 ~ 60%. Isolation voltage shall be measured using the following method.
- (1) Short between anode and cathode on the primary side and between collector and emitter on the secondary side.
- (2) The isolation voltage tester with zero-cross circuit shall be used.
- (3) The waveform of applied voltage shall be a sine wave.
- 2. For 10 Seconds
- 3. Current Transfer Ratio (CTR) is defined as the ration of output collector current, Io, to the forward LED input current, IF, times 100%.
- 4. Pin 7 open.
- 5. Instantaneous common mode rejection voltage "output (1)" represents a common mode voltage variation that can hold the output above (1) level (Vo>2.0V).Instantaneous common mode rejection voltage "output (0)" represents a common mode voltage variation that can hold the output above (0) level (Vo<0.8V).
- 6. Device considered a two terminal device. Pins 1, 2, 3 and 4 shorted together and Pins 5, 6, 7 and 8 shorted together.



7. SWITCHING TIME TEST CIRCUIT

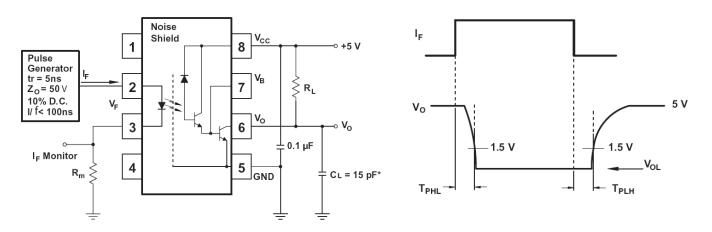


Figure 1: Single Channel Test Circuit for t_{PHL} and t_{PLH}

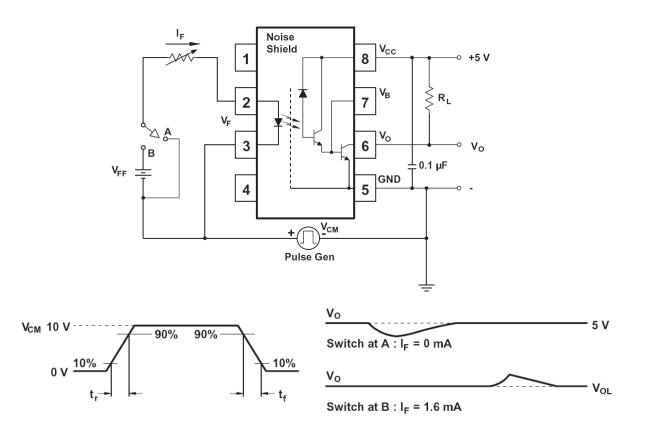


Figure 2: Single Channel Test Circuit for Common Mode Transient Immunity



8. CHARACTERISTIC CURVES

Figure 3: DC transfer characteristics

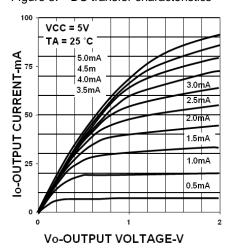


Figure 4: output current vs. input diode forward

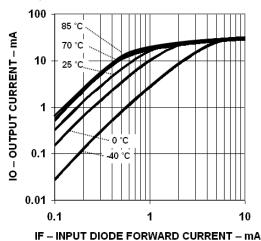
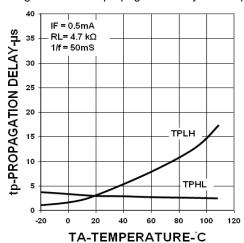


Figure 5: 6N139 propagation delay vs. temperature



Photocoupler 6N138-L 6N139-L series

Figure 6: current transfer ratio vs. forward current

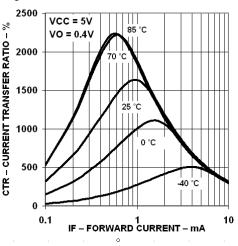


Figure 7: current transfer ratio vs. forward current

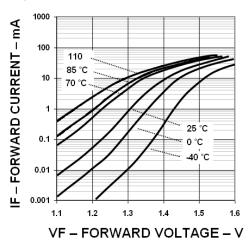


Figure 8: 6N138 propagation delay vs. temperature

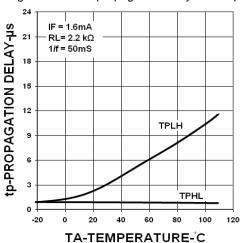




Figure 9: 6N139 propagation delay vs. temperature

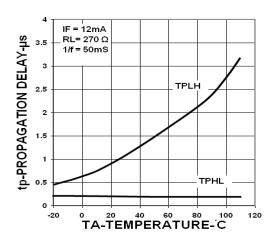


Figure 11: Forward voltage vs. temperature

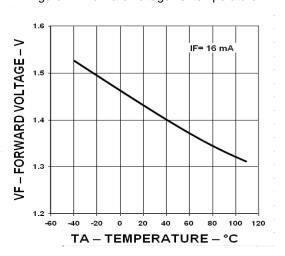


Figure 10: Nonsaturated rise and fall time vs. load resistance

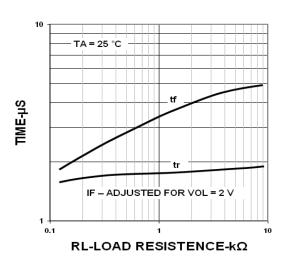
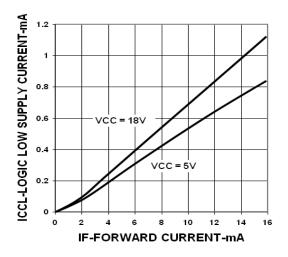


Figure 12: Logic low supply current vs. forward current



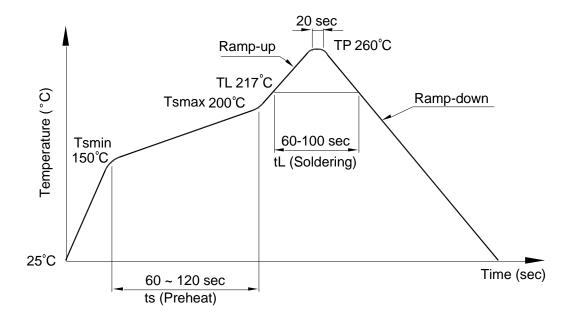


9. TEMPERATURE PROFILE OF SOLDERING

9.1 IR Reflow soldering (JEDEC-STD-020C compliant)

One time soldering reflow is recommended within the condition of temperature and time profile shown below. Do not solder more than three times.

Profile item	Conditions			
Preheat				
- Temperature Min (T _{Smin})	150°C			
- Temperature Max (T _{Smax})	200°C			
- Time (min to max) (ts)	90±30 sec			
Soldering zone				
- Temperature (T _L)	217°C			
- Time (t _L)	60 ~ 100 sec			
Peak Temperature (T _P)	260°C			
Ramp-up rate	3°C / sec max.			
Ramp-down rate	3~6°C / sec			





9.2 Wave soldering (JEDEC22A111 compliant)

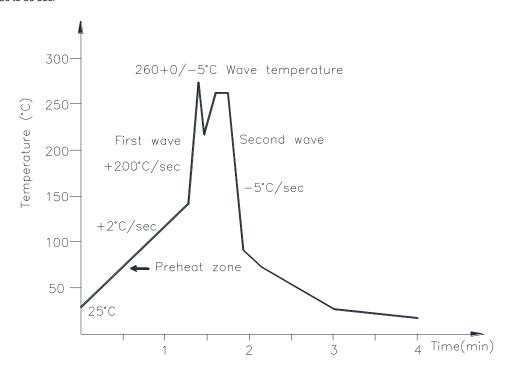
One time soldering is recommended within the condition of temperature.

Temperature: 260+0/-5°C

Time: 10 sec.

Preheat temperature:25 to 140°C

Preheat time: 30 to 80 sec.



9.3 Hand soldering by soldering iron

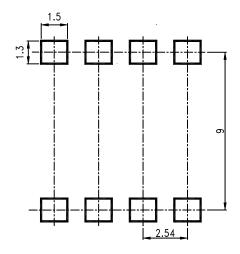
Allow single lead soldering in every single process. One time soldering is recommended.

Temperature: 380+0/-5°C

Time: 3 sec max.



10. RECOMMENDED FOOT PRINT PATTERNS (MOUNT PAD)

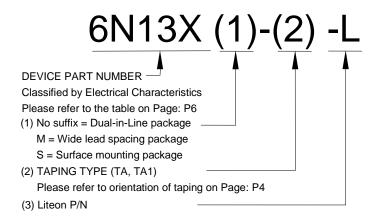


Note:

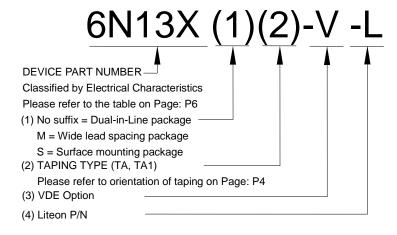
Dimensions in millimeters.



11. NAMING RULE



Example: 6N138S-TA1-L, 6N139S-TA1-L



Example: 6N138STA1-V-L, 6N139STA1-V-L

12. NOTES

- LiteOn is continually improving the quality, reliability, function or design and LiteOn reserves the right to make changes without further notices.
- The products shown in this publication are designed for the general use in electronic applications such as office automation equipment, communications devices, audio/visual equipment, electrical application and instrumentation.
- For equipment/devices where high reliability or safety is required, such as space applications, nuclear power control equipment, medical equipment, etc, please contact our sales representatives.
- When requiring a device for any "specific" application, please contact our sales in advice.
- If there are any questions about the contents of this publication, please contact us at your convenience.
- The contents described herein are subject to change without prior notice.
- Immerge unit's body in solder paste is not recommended.